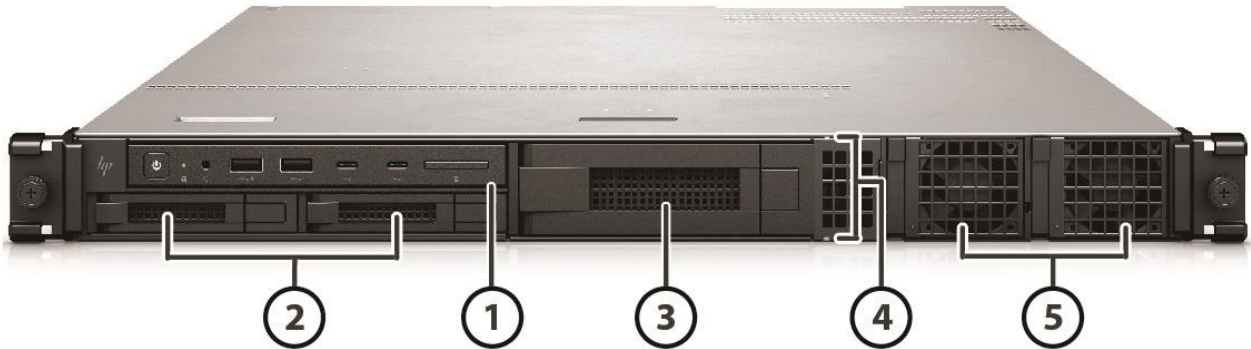


Overview

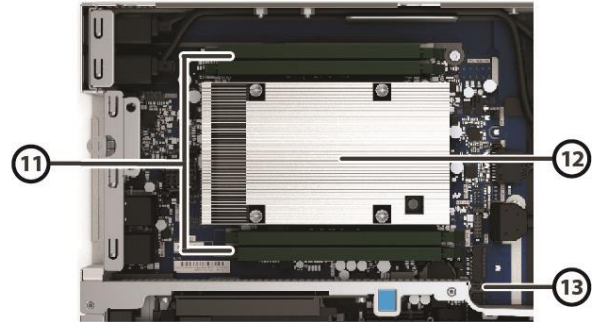
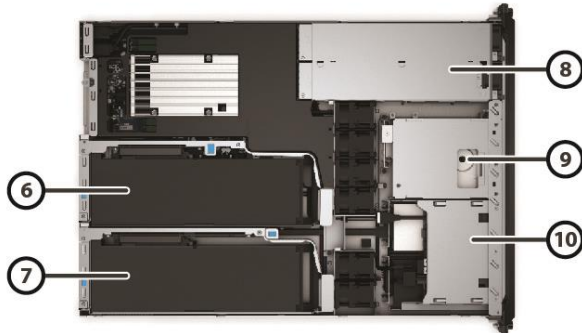
HP ZCentral 4R Workstation



Front view

1. Front I/O module options
 - Premium (optional - shown here): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C®, Headset audio, (Left-most Type-A port has charging capability), Smart Card not supported
 - Standard (optional): power button, 4 USB 3.1 G1 Type-A (left-most Type-A port has charging capability), Headset audio, Smart Card not supported
2. 2 x 2.5" external drive bays
3. 1 x 3.5" external drive bay (can be configured with 1 x 3.5" drive or 2 x 2.5" drives)
4. Locator LED
5. 2 x external 675W PSU bays
 - ENTRY**
Contains one (1) PSU 675W power supply.
 - ENTRY REDUNDANT**
Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.
 - HIGH END**
Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

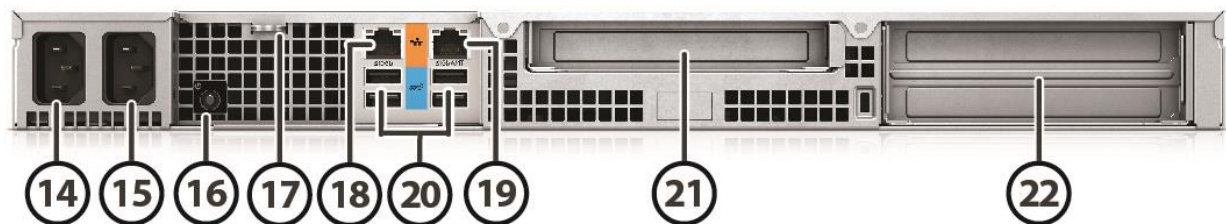
Overview



Internal views

- | | |
|---|---|
| 6. Single Slot Riser (1 PCIe G3 x16); includes a single 6+2 auxiliary power cable | 11. Four DIMM slots; DDR4- 2933 ECC Reg RAM |
| 7. Dual Slot Riser* (1 PCIe G3 x16; 1 PCIe G3 x16 wired as x8); includes an additional dual 6+2 auxiliary power cable | 12. Intel® Xeon® Processors: W-2200 family |
| 8. Power supply bays | 13. Two PCIe G3 x4 M.2 for SSDs |
| 9. 3.5" drive bay | |
| 10. Two 2.5" drive bays | |

*Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes an additional dual 6+2 pin auxiliary power cable



Rear view

- | | |
|--|---|
| 14. Primary power supply cable connector | 19. 1/2.5/5/10GbE RJ-45 |
| 15. Secondary power supply cable connector | 20. 4x USB 3.1 G1 Type-A |
| 16. Rear power button | 21. Single Slot Riser (1 PCIe G3 x16) |
| 17. Padlock loop | 22. Dual Slot Riser* (1 PCIe G3 x16; 1 PCIe G3 x16 wired as x8) |

Overview

18. 1GbE RJ-45 (AMT)

*Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary power cable

Overview

Form Factor Operating Systems

1U Rackable Workstation

Preinstalled:

- Windows 10 Pro 64 for Workstations*
- Ubuntu Linux® 20.04**
- HP Linux-ready (minimal OS ready for customer OS installation)***

Supported:

- Red Hat® Enterprise Linux® Desktop 7.4 (Paper license with 1 year support)
- Red Hat® Enterprise Linux® Desktop 8.0 (Paper license with 1 year support)
- Ubuntu 18.04 LTS
- Ubuntu 20.04 LTS

Supported Version:

- HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see: <https://support.hp.com/document/c05195282>.

For detailed Linux® OS/hardware support information, see:
http://www.hp.com/support/linux_hardware_matrix

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

**Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

***For detailed Linux® OS/hardware support information, see:
http://www.hp.com/support/linux_hardware_matrix.

Note: In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows® 7 operating system on products configured with Intel® and AMD 7th Generation and forward processors or provide any Windows® 8 or Windows® 7 drivers on <http://www.support.hp.com>

Supported Components

Available Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper-Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz) ¹	Intel® Turbo Boost Max Technology 3.0 (GHz) ¹	TDP (W)
Intel® Xeon® W Processors											
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	165
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120

¹Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

NOTE: Processors that do not have certain turbo functionality are denoted as N/A.

Available Processors

Disclaimers

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Supported Components

Expansion Slots (see system board section for more details)	<p>Slot 1 (SSR*): PCI Express Gen3 x16 from CPU</p> <p>Slot 2 (DSR*): PCI Express Gen3 x16 from CPU - operates as x8 if Slot 3 is loaded</p> <p>Slot 3 (DSR*): PCI Express Gen3 x16 (wired as x8) from CPU</p> <p>M.2 Slot 1: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-M</p> <p>M.2 Slot 2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-M</p> <p>*SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable</p> <p>*DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary power cable</p>
Expansion Bays (see storage section for more details)	<p>2 external 2.5" bays</p> <p>1 external 3.5" bay (can be configured with 1 x 3.5" drive or 2 x 2.5" drives)</p>
Front I/O	<ul style="list-style-type: none"> • Base: Power button with power/fault LED, Drive activity LED, 1 Headset audio port, 4 USB 3.1 G1 Type A (1 charging, provides 1.5A at 5V) • Premium (optional): Power button with power/fault LED, Drive activity LED, 1 Headset audio port, 2 USB 3.1 G1 Type-A (1 charging, provides 1.5A at 5V), 2 USB 3.1 G2 Type-C® (each provides 3A at 5V) • SD Card Reader is not supported
Internal I/O	1 USB 2.0 dual-port header
Rear I/O	<p>4x USB 3.1 G1 Type-A*</p> <p>1x 1/2.5/5/10GbE LAN port</p> <p>1x 1GbE LAN port (supporting Intel AMT)</p> <p>*All rear I/O motherboard USB-A ports are 0.9A at 5V</p>
Interfaces Supported	<p>4-channel SATA interface (6 @ 6.0 Gb/s)</p> <p>USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)</p>
On-board RAID Support	<p>SATA RAID 0 Striped Array Configuration</p> <p>SATA RAID 1 Mirrored Array Configuration</p> <p>SATA RAID 10 Striped/Mirrored Configuration</p>
Chassis Dimensions	
Base footprint without front bezel and rack brackets (H x W x D)	<p>H: 1.685" (42.8mm)</p> <p>W: 17.25" (438.15mm)</p> <p>D: 24.61" (625mm)</p>
With front bezel and rack brackets (H x W x D)	<p>H: 1.685" (42.8mm)</p> <p>W: 19.17" (486.81mm)</p> <p>D: 25.42" (645.70mm)</p>
Packaged Dimensions	<p>H: 7.28" (185mm)</p> <p>W: 23.22" (590mm)</p> <p>D: 32.48" (825mm)</p>
Palletization Profile	<p>2 units per layer x 10 layers = 20 units per pallet</p> <p>1200x1000x1980mm(included pallet)</p>
Rack Dimensions	1U
Weight	<p>Exact weights depend upon configuration (System weight only).</p> <p>Minimum: 10.7 kg (23.7 lbs.)</p> <p>Standard: 11.7 kg (25.9 lbs)</p> <p>Maximum: 13.6 kg (30 lbs)</p>
Temperature	<p>Non-operating: -40° to 60° C (-40° to 140° F)</p> <p>Operating: 5° to 35° C (40° to 95° F)</p>

Supported Components

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation
 Maximum rate of change: 10 °C/hr
 No direct sustained sunlight

Humidity

Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb
 Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non-pressurized)

Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)
 Operating (with only Solid-State Drives): 5,000 m (16,404 feet)
 Non-operating: 12,192 m (40,000 feet)
 Maximum operating temperature is reduced as altitude increases. See Temperature for details.

Power Supply

The ZCentral 4R 675W power supply efficiency report can be found at this link:
<https://clearesult5.sharepoint.com/:b/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-My6Ng?e=cPfbnt>

ENTRY

Contains one (1) PSU 675W power supply.

ENTRY REDUNDANT

Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

HIGH-END

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

Workstation ISV Certifications

See the latest list of certifications at
<http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html>

Processors

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® Xeon® W-Series CPU				
Intel® Xeon® W-2295 3.0 2933 18C CPU	Y	N		
Intel® Xeon® W-2275 3.3 2933 14C CPU	Y	N		
Intel® Xeon® W-2265 3.5 2933 12C CPU	Y	N		
Intel® Xeon® W-2255 3.7 2933 10C CPU	Y	N		
Intel® Xeon® W-2245 3.9 2933 8C CPU	Y	N		
Intel® Xeon® W-2235 3.8 2933 6C CPU	Y	N		
Intel® Xeon® W-2225 4.1 2933 4C CPU	Y	N		
Intel® Xeon® W-2223 3.6 2933 4C CPU	Y	N		

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Supported Components

Storage / Hard Drives*

SATA Hard Drives	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
SATA (Serial ATA) Hard Drives for HP Workstations				
1TB SATA 7200RPM Ent 3.5" HDD	Y	Y	W0R10AA	
2TB SATA 7200RPM Ent 3.5" HDD	Y	Y	QB576AA	
4TB SATA 7200RPM Ent 3.5" HDD	Y	Y	K4T76AA	
*For storage drives, GB = 1 billion bytes. TB = one trillion bytes. Actual formatted capacity is less. Up to 35GB of disk space is reserved for system recovery software.				

SATA Solid State Drives

SATA Solid State Drives	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Solid State Drives (SSDs) for Workstations				
HP 256GB SATA SSD	Y	Y	A3D26AA	
HP 512GB SATA SSD	Y	Y	D8F30AA	
HP 1TB SATA SSD	Y	Y	F3C96AA	
HP 2TB SATA SSD	N	Y	Y6P08AA	
HP 240GB SATA Ent SSD	Y	Y	T3U07AA	
HP 480GB SATA Ent SSD	Y	Y	T3U08AA	
HP 960GB SATA Ent SSD	Y	Y	1W6P8AA	
HP 1920GB SATA Ent SSD	Y	Y	1W6P9AA	
HP 512GB SATA SED OPAL2 SSD	N	Y	N8T26AA	
HP 1TB SATA SSD	Y	Y	F3C96AA	

PCIe Solid State Drives

PCIe Solid State Drives	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Z Turbo Drive Dual Pro				
HP Z Turbo Drive Dual Pro 512GB TLC SSD	Y	Y	4YF61AA	
HP Z Turbo Drive Dual Pro 1TB TLC SSD	Y	Y	4YF62AA	
HP Z Turbo Drive Dual Pro 2TB TLC SSD	Y	Y	4YF63AA	
HP Z Turbo 256GB TLC 4R Kit SSD	Y	Y	2E3R0AA	
HP Z Turbo 512GB TLC 4R Kit SSD	Y	Y	2E3R1AA	
HP Z Turbo 1TB TLC 4R Kit SSD	Y	Y	2E3R2AA	
HP Z Turbo 2TB TLC 4R Kit SSD	Y	Y	2E3R3AA	
HP Z Turbo 512GB SED TLC 4R Kit SSD	Y	Y	2E3R4AA	
HP Z Turbo 256GB SED TLC 4R Kit SSD	Y	Y	2E3R5AA	

Supported Components

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® Virtual RAID on CPU (Intel® VROC) for NVMe Intel® VROC NVMe SSD Standard Controller Module	N	Y	3FJ80AA	1

NOTE 1: Enables RAID 0, 1 & 10

Graphics

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP miniDP-to-DP Adapter	Y	Y	2MY05AA	
HP miniDP-to-DP Adapter (12-pack)	Y	N	2KW87A6	
Entry 3D				
NVIDIA® Quadro® P400 2GB Graphics	Y	Y	1ME43AA	1
Mid-range 3D				
NVIDIA® Quadro® P1000 4GB Graphics	Y	Y	1ME01AA	1
NVIDIA® Quadro® P2200 5GB Graphics	Y	Y	6YT67AA	1
High-End 3D				
NVIDIA® Quadro® RTX 4000 8GB Graphics	Y	Y	5JV89AA	1
Ultra High-End 3D				
NVIDIA® Quadro® RTX 5000 16GB Graphics	Y	Y	5JH81AA	2,3
NVIDIA® Quadro® RTX 6000 24GB Graphics	Y	Y	5JH80AA	2
NVIDIA® Quadro® RTX 8000 48GB Graphics	Y	Y	6NB51AA	2

NOTE 1: Dual graphics configuration requires addition of Dual Slot Riser and High End Chassis with 1350W PSU; Single Slot Riser includes single 6+2 pin auxiliary power cable. Dual Slot riser includes an additional dual 6+2 pin auxiliary power cable.

NOTE 2: Dual Graphics not Supported. Requires addition of Dual Slot Riser and High End Chassis with 1350W PSU. Dual Slot riser includes an additional dual 6+2 pin auxiliary power cable.

NOTE 3: The RTX 5000 can be configured with Redundant Power Supplies only when configured with processors with TDP ≤ 130W.

Supported Components

Memory

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
8GB (1x8GB) DDR4- 2933 ECC Reg RAM	Y	Y	5YZ56AA/AT	1
16GB (1x16GB) DDR4- 2933 ECC Reg RAM	Y	Y	5YZ54AA/AT	1
32GB (1x32GB) DDR4- 2933 ECC Reg RAM	Y	Y	5YZ55AA/AT	1
64GB (1x64GB) DDR4- 2933 ECC Reg RAM	Y	Y	5YZ57AA/AT	1

Factory Configured System Memory Solutions

- 8GB (1x8GB) DDR4
- 16GB (1x16GB) DDR4
- 16GB (2x8GB) DDR4
- 24GB (3x8GB) DDR4
- 32GB (2x16GB) DDR4
- 32GB (4x8GB) DDR4
- 64GB (2x32GB) DDR4
- 64GB (4x16GB) DDR4
- 128GB (2x64GB) DDR4
- 128GB (4x32GB) DDR4
- 256GB (4x64GB) DDR4

NOTE 1: ONLY DDR4 RDIMMs are supported.

NOTE: Factory-configured CTO (xxxxxAV) and aftermarket AMO (xxxxxAA, xxxxxAT) HP memory part numbers designated as "2933" will be transitioned to use "3200" speed memory components. This does not affect HP part number availability, nor does it affect system performance or operation. All hardware configurations currently supporting HP memory part numbers designated as "2933" have been tested to work with "3200" memory and are fully-supported by HP under standard support terms.

Multimedia and Audio Devices

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Realtek HD ALC3601 Audio	Y	N		

Supported Components

Networking and Communications

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Intel® Ethernet I219-LM Single Port 1Gb NIC	Y	N		
Integrated Marvell® AQC-107 Single Port 1/2.5/5/10GbE NIC	Y	N		
Intel® I210-T1 Single Port 1GbE	Y	Y	E0X95AA	
Intel® X550-T2 Dual Port 10GbE NIC	Y	Y	1QL46AA	
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Y	Y	1C7Q2AA	

Racking and Physical Security

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ZCentral 4R Front Bezel/Security	Y	Y	16G58AA	
HP ZCentral 4R Rail Rack Kit	Y	Y	16G60AA	
HP Rack Cable Management Arm	N	Y	35Z34AA	

Input Devices

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	Y	Y	N3R88AA	
USB Business Slim Wired Keyboard	Y	Y	N3R87AA	
USB Premium Wired Keyboard	Y	Y	Z9N40AA	

Supported Components

Other Hardware

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ENERGY STAR® Certified Configuration	Y	N		
HP ZCentral 4R 2 nd 675W Power Supply	Y	Y	1C9J6AA	
HP ZCentral 4R Dual PCIe Slot Riser Kit	Y	Y	16G54AA	
HP ZCentral 4R Power Cord Kit	Y	Y	1N1D4AA	
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	Y	Y	16G59AA	
HP Serial Port and PS/2 Port	N	Y	141K9AA	
HP Internal USB Port Kit		Y	EM165AA	1
HP ZCentral 4R 2.5" Dual Drive Cage Adapter		Y	16G55AA	
HP ZCentral 4R 2.5" Drive Carrier		Y	16G56AA	
HP ZCentral 4R 3.5" Drive Carrier		Y	16G57AA	

NOTE 1: The HP Internal USB Port Kit has a single USB 2.0 type A connector

Software

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ZCentral Remote Boost	Y	N		2
HP Sure Start Gen6	Y	N		7
HP Sure Sense	Y	N		3
HP Sure Click	Y	N		4
HP PC Hardware Diagnostics UEFI	Y	N		
HP PC Hardware Diagnostics Windows	Y	N		
HP Performance Advisor	Y	N		8
HP Client Security Manager Gen5	N	Y		6
HP Manageability Integration Kit Gen4	N	Y		5
Sobey Video Editing SW	N	Y		1

NOTE 1: China Only

NOTE 2: HP ZCentral Remote Boost does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

NOTE 3: HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

NOTE 4: HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details.

NOTE 5: HP Manageability Integration Kit can be downloaded from

<http://www.hp.com/go/clientmanagement>.

NOTE 6: HP Client Security Manager Gen5 requires Windows and is available on the select HP Elite and Pro PCs.

NOTE 7: HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.

NOTE 8: HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: <https://www8.hp.com/us/en/workstations/performance-advisor.html>

Operating Systems

Windows 10 Pro 64 for Workstations

Support Notes

Supported Components

Red Hat® Enterprise Linux® Desktop 7.4	1, 2
Red Hat® Enterprise Linux® Desktop 8.0	1, 2
Ubuntu 18.04 LTS	2
Ubuntu 20.04 LTS	2

NOTE 1: Paper license with 1 year support

NOTE 2: For detailed Linux® OS/hardware support information, see:
http://www.hp.com/support/linux_hardware_matrix

System Technical Specifications

System Board

System Board Form Factor

L-Shaped
11.71 x 12.15 inches

Processor Socket Chipset

Single LGA2066 R4
Intel® Xeon® W Processor Family
Intel® C422 Chipset

Super I/O Controller

Nuvoton NPCD315HA0DX (SIO-15)

Memory Expansion Slots

4 DDR4 memory slots

Memory Type Supported

DDR4, RDIMM (Registered), ECC

Memory Modes

Channel Interleaved

Memory Speed Supported

2933MT/s, 2666MT/s and 2400MT/s

Memory Protection

ECC available on data, parity on address and command

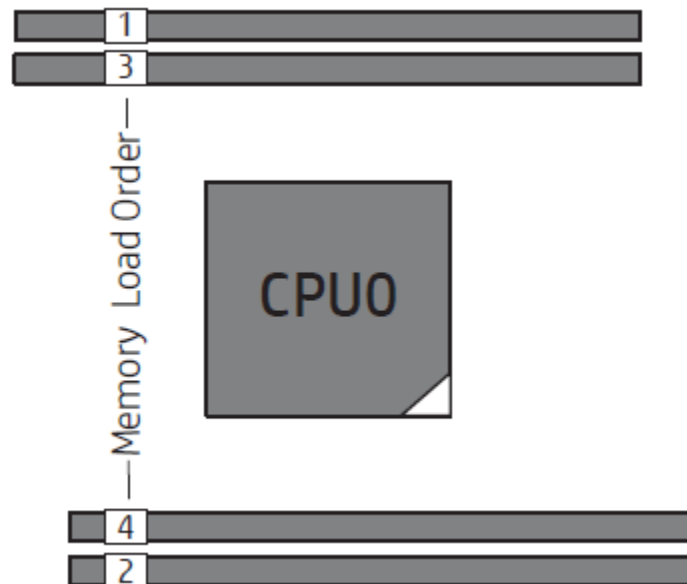
Maximum Memory

Supports up to 256GB

Memory Configuration (Supported)

Only Registered DIMMs are supported.

Memory Load Order



Note on Maximum Memory

Maximum memory capacities assume 64-bit operating systems such as Windows 10 Pro 64-bit, Windows 7 Professional 64-bit.

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

System Technical Specifications

PCI Express Connectors	Slot 1 (SSR*):	PCI Express Gen3 x16 supplied by CPU
	Slot 2 (DSR*):	PCI Express Gen3 x16 supplied by CPU (operates as x8 if Slot 3 is loaded)
	Slot 3 (DSR*):	PCI Express Gen3 x16 (wired as x8) supplied by CPU
	M.2 Slot 1:	PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-M
	M.2 Slot 2:	PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-M
	*SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable	
	*DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary power cable	
Supported Drive Interfaces		
SATA	4 SATA @ 6GB/s, supports RAID 0,1, and 10 Factory integrated Intel® SATA RAID is Microsoft Windows only	
Serial Attached SCSI	Not supported	
Factory Configured RAID	<ul style="list-style-type: none"> • RAID 0 striped array • RAID 1 mirrored array • RAID 10 striped and mirrored array *HW RAID functionality not supported by Linux®. Use SW RAID functionality provided in the Red Hat® Operating system instead.	
Integrated Graphics	No	
Network Controller	Marvell AQtion AQC107 PCIe 1/2.5/5/10GBASE-T LAN Intel® I219-LM PCIe GbE LAN supports the following management functionalities: Intel AMT11.12, TXT, DASH 1.1, WOL, VLAN, Teaming and PXE 2.1	
External SATA (eSATA)	No	
IDE connector	No	
Floppy connector	No	
Serial and PS2	1 internal header	
2nd Serial	No	
Parallel	No	
AUX IN (audio)	No	
IEEE 1394 Connector(s)	No	
USB Connector(s)		
Front	Front USB depends on which FIO module is selected: <ul style="list-style-type: none"> - Standard: 4 USB 3.1 G1 Type A (1 charging) - Premium: 2 USB 3.1 G2 Type C®, 2 USB 3.1 G1 Type A (1 charging) 	
Rear	4 USB 3.1 G1 Type A 1 USB 2.0 single-port header 1x USB 2.0 dual-port header	
HD Integrated Audio	Realtek ALC3601-CG	
Flash ROM	Yes	

System Technical Specifications

Fan Headers	Yes
Front Control Panel/Speaker Header	Yes
CMOS Battery Holder - Lithium	Yes
Integrated Trusted Platform Module	Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670) Common Criteria EAL4+ Certified Convertible to FIPS 140-2 Certified mode through firmware v7.85 TPM Certified products list: https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/
Power Supply Headers	Yes
Power Switch, Power LED & Hard Drive LED Header	Yes
Clear Password Jumper	Yes
Serial Port	1 internal header
Parallel Port	No
Keyboard/Mouse	USB (PS/2 supported via AMO kit)
Hood Lock Header	No
Hood Sensor Header	Yes
AUX OUT (audio)	(Front Audio) Headset

System Technical Specifications

Power Supply	The HP ZCentral 4R Workstation contains up to two (2) 675 watt wide-ranging, active Power Factor Correction, 90% Efficient PSUs.	
	The 675W power supply efficiency report can be found at this link: https://cleareresult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-My6Ng?e=cPfbnt	
	ENTRY Contains one (1) PSU 675W power supply.	
	ENTRY REDUNDANT Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.	
	HIGH END Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).	
Power Supply	675W 90% Efficient, Custom PSU (Wide-Ranging, Active PFC)	
Operating Voltage Range	90–269 VAC	
Rated Voltage Range	100–240 VAC	118 VAC
Rated Line Frequency	50–60 Hz	400 Hz
Operating Line Frequency Range	47–66 Hz	393–407 Hz
Rated Input Current	9A @100–127 VAC 4.5A @ 200–240 VAC	7A @ 118VAC
Heat Dissipation (Configuration and software dependent)	Typical = 1832 btu/hr Max = 2647 btu/hr	
Power Supply Fan	40x40 mm variable speed	
ENERGY STAR® Certified (Configuration dependent)	Yes 90% Efficient	
80 PLUS® Compliant	The power supply efficiency report can be found at this link: https://cleareresult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-My6Ng?e=cPfbnt	
FEMP Standby Power Compliant @115V <1W in S5 – Power Off)	Yes, 1 PSU only	Yes, 1 PSU only
EuP Compliant @ 230V (<0.5 W in S5 – Power Off)	N/A for EMC Class A Equipment	N/A for EMC Class A Equipment
Power Consumption in sleep mode (as defined by ENERGY STAR®) – Suspend to RAM (S3) (Instantly Available PC)	<10W	<10W
Built-in Self Test LED	No	No

System Technical Specifications

**Surge Tolerant Full Ranging
Power Supply
(withstands power surges up
to 2000V)**

Yes

Yes

System Technical Specifications

System Configuration

Example ZCentral 4R Workstation Configuration #1 ENERGY STAR® Certified	Processor	Intel Xeon W-2223 4C 3.6GHz					
	Memory	1x 8GB DDR4 2933 (Registered DIMM)					
	Graphics	1x NVIDIA Quadro P400					
	Disks / Optical	1x HP Zturbo M.2 512GB TLC SSD					
	Power Supply	1x 675W					
	Other	N/A					
Energy Consumption		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	45.219		45.379		45.143	
	Windows Busy Typ(S0)	144.871		142.362		140.95	
	Windows Busy Max (S0)	150.762		149.580		148.992	
	Sleep (S3)	5.540	5.321	5.548	5.322	5.535	5.322
	Off (S5)	2.945	2.524	3.13	3.005	3.112	2.998
	Zero Power Mode (ErP)	0.300		0.314		0.301	
Heat Dissipation (Btu/hr)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
	Windows Idle (S0)	154.287		154.833		154.027	
	Windows Busy Typ(S0)	494.299		485.732		480.92	
	Windows Busy Max (S0)	514.399		510.366		508.36	
	Sleep (S3)	18.902	18.155	18.929	18.129	18.885	18.158
	Off (S5)	10.631	10.239	10.679	10.653	10.618	10.229
	Zero Power Mode (ErP)	1.023		1.071		1.027	

System Technical Specifications

Example ZCentral 4R Workstation Configuration #2 ENERGY STAR® Certified	Processor	1x Intel Xeon W-2245 8C 3.9GHz					
	Memory	2x16GB DDR4-2933 (Registered DIMM)					
	Graphics	1x NVIDIA Quadro P2200					
	Disks / Optical	1x ZTurbo 256GB M.2 SSD; 1x 2TB 7200 SATA Enterprise 3.5in HDD					
	Power Supply	1x 675W					
	Other	N/A					
Energy Consumption (Watts)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	53.157		53.368		52.983	
	Windows Busy Typ(S0)	272.91		270.65		267.35	
	Windows Busy Max (S0)	279.43		280.36		279.37	
	Sleep (S3)	5.314	5.375	5.328	5.371	5.321	5.381
	Off (S5)	2.945	2.908	2.943	2.9	2.963	2.902
	Zero Power Mode (ErP)	0.301		0.312		0.303	
Heat Dissipation (Btu/hr)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
	Windows Idle (S0)	181.371		182.091		184.374	
	Windows Busy Typ(S0)	931.168		923.457		912.198	
	Windows Busy Max (S0)	953.415		956.58		953.21	
	Sleep (S3)	18.131	18.339	18.179	18.325	18.155	18.359
	Off (S5)	10.048	9.922	10.041	9.894	10.017	9.901
	Zero Power Mode (ErP)	1.027		1.065		1.034	

System Technical Specifications

Example ZCentral 4R Workstation Configuration #3	Processor	1x Intel Xeon W-2255 10C 3.7GHz					
	Memory	4x 16GB DDR4-2933 (Registered DIMM)					
	Graphics	1x NVIDIA Quadro RTX4000					
	Disks/Optical	1x Zturbo 512GB M.2 SSD; 1x 4TB 7200 Enterprise SATA HDD					
	Power Supply	1x 675W					
	Other	N/A					
Energy Consumption (Watts)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	56.77		57.035		56.763	
	Windows Busy Typ(S0)	335.24		333.25		330.97	
	Windows Busy Max (S0)	345.36		344.89		344.67	
	Sleep (S3)	5.883	5.829	5.883	5.842	5.88	5.835
	Off (S5)	2.949	2.915	2.948	2.918	2.945	2.912
	Zero Power Mode (ErP)	0.303		0.316		0.306	
Heat Dissipation (Btu/hr)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
	Windows Idle (S0)	193.699		194.603		193.583	
	Windows Busy Typ(S0)	1143.839		1137.049		1129.27	
	Windows Busy Max (S0)	1178.36		1176.76		1176.01	
	Sleep (S3)	20.072	19.888	20.072	19.932	20.062	20.072
	Off (S5)	10.061	9.945	10.058	9.956	10.048	10.061
	Zero Power Mode (ErP)	1.034		1.078		1.044	

System Technical Specifications

Example ZCentral 4R Workstation Configuration #4	Processor	1x Intel Xeon W-2295 18C 3.0GHz					
	Memory	4x 32GB DDR4-2933 (Registered DIMM)					
	Graphics	1x NVIDIA RTX8000					
	Disks / Optical	2x ZTurbo 2TB M.2 SSD; 2x ZTurbo 2TB Z Dual Pro PCIe SSD; 4x 1TB 2.5in SATA SSD					
	Power Supply	2x 675W PSU					
	Other	N/A					
Energy Consumption (Watts)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	60.489		60.889		60.413	
	Windows Busy Typ(S0)	464.213		458.512		461.441	
	Windows Busy Max (S0)	495.789		487.213		491.220	
	Sleep (S3)	5.893	5.819	5.990	5.831	5.887	5.412
	Off (S5)	3.312	3.012	3.418	3.111	3.303	3.045
	Zero Power Mode (ErP)	0.523		0.774		0.517	
Heat Dissipation (Btu/hr)		115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
	Windows Idle (S0)	206.388		207.753		206.129	
	Windows Busy Typ(S0)	1583.894		1563.984		1574.4367	
	Windows Busy Max (S0)	1691.632		1662.370		1676.043	
	Sleep (S3)	20.107	19.854	20.437	19.895	20.086	18.465
	Off (S5)	11.301	10.277	11.662	10.615	11.269	10.389
	Zero Power Mode (ErP)	1.7844		2.6411		1.7641	

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

System Technical Specifications

DECLARED NOISE EMISSIONS

Declared Noise Emissions (Entry-level and High-end configurations)			
System Configuration (Entry level)	Processor Info	Intel® Xeon® W-2255 3.7GHz 2933MHz 10C CPU	
	Memory Info	256GB (4x64GB) DDR4-2933 ECC Reg RAM	
	Graphics Info	1-NVIDIA® Quadro® RTX 4000	
	Disks/Optical	1-4TB SATA 7200RPM 3.5" HDD / 2-1TB 2.5" SSD / 2-2TB PCIe M.2 SSD	
	Power Supply	Single 675W	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	4.9	34
	Hard drive Operating (random reads)	4.9	34

NOTE: Higher noise levels may be experienced with non-HP approved graphic card(s). Some consumer graphics cards have side blowing fans that may heat up thermal sensor(s) on the mother board causing fans to ramp.

System Technical Specifications

ENVIRONMENTAL DATA

Environmental Requirements	Temperature	<p>Non-operating: -40° to 60° C (-40° to 140° F) Operating: 5° to 35° C (40° to 95° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Maximum rate of change: 10 °C/hr No direct sustained sunlight</p>
	Humidity	<p>Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb</p>
	Maximum Altitude	<p>Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Temperature for details.</p>
	Shock (non-repetitive)	<p>Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g) Non-operating square: 422 cm/s, 20g</p>
	Vibration	<p>Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz</p>

Physical Security and Serviceability

Access Panel	<p>Tool-less Includes system board and memory information.</p>
Hard Drives	Screw-mounted
Expansion Cards	<p>Expansion card cage removal/insertion into system is tool-less Expansion card access requires removal of screw-mounted retainer bracket</p>
Processor Socket	Tool-less
Blue User Touch Points	Yes, on primary serviceable components.
Color-coordinated Cables and Connectors	Yes
Memory DIMM Connectors	Tool-less
System Board	Screw-mounted
Dual Color Power/Failure LED	Yes
HDD Activity LED	<p>Yes Note: HDD Activity LED is not dual-color</p>
Configuration Record SW	Yes
Over-Temp Warning on Screen	Yes, at POST screen on reboot
Restore CD/DVD Set	Restores the computer to its original factory shipping image; can be obtained via HP Support.
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 4 seconds
Padlock Support	<p>Yes (optional): Locks top cover and secures chassis from theft 7.0 mm (0.2756 in) diameter padlock loop at rear of system</p>
Cable Lock Support	<p>Yes, Kensington Cable Lock (optional): Secures chassis from theft 3 mm x 7 mm slot at rear of system</p>

System Technical Specifications

Universal Chassis Clamp Lock Support	No
Chassis Interlock Sensor	Yes Sensor detects when the access panel has been removed. The access panel must be installed for the system to power ON.
Serial, USB, Audio, Network, Enable/Disable Port Control	Yes, enables or disables serial, USB, audio, and network ports
Removable Media Write/Boot Control	Yes, prevents ability to boot from removable media on supported devices (and can disable writes to media)
Power-On Password Setup Password	Yes, prevents an unauthorized person from booting up the workstation Yes, prevents an unauthorized person from changing the workstation configuration
3.3V Aux Power LED on System PCA	Yes
NIC LEDs (integrated) (Green & Amber)	Yes
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less
Power Supply Diagnostic LED	Yes Solid Green (OK); Blinking Green (Standby); Red (Fault); Off (No AC Power/PSU Failure)
Front Power Button	Yes, ACPI multi-function
Rear Power Button	Yes
System Locator LED	Yes, blue
Front Power LED	Yes, white (normal), red (fault)
Front Hard Drive Activity LED	Yes, white
Internal Speaker	Yes
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
Cooling Solutions	Air cooled forced convection heatsinks
Power Supply Fan	40 mm x 40 mm x 28 mm (non-serviceable)
Chassis Fans	40 mm x 40 mm x 56 mm (serviceable)
HP PC Hardware Diagnostics UEFI	HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot and is available as a download from HP Support.
Access Panel Key Lock	No
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI). <ul style="list-style-type: none"> • Allows the system to wake from a low-power mode. • Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system
Trusted Platform Module Chip	Infineon TPM 2.0 Certified
Integrated Chassis Handles	No
Power Supply	Tool-less
PCIe Card Retention	Yes, rear (all), middle (all), front (full-length cards with extender)
Flash ROM	Yes
Diagnostic Power Switch LED on board	Yes

System Technical Specifications

Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder	Yes

BIOS

BIOS 32-bit Services	Standard BIOS 32-bit Service Directory Proposal v0.4
PCI 3.0 Support	Full BIOS support for PCI Express through industry standard interfaces.
ATAPI	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01.
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.
Replicated Setup	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
SMBIOS	System Management BIOS 3.2, for system management information.
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes: <ul style="list-style-type: none"> • NORMAL - normal temperature ranges. • ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. • SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 5.0 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time.
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.

System Technical Specifications

System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with local keyboard mappings.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
Industry Standard Specification Support	
Industry Standard UEFI Specification Revision	Revision Supported by the BIOS 2.6
ACPI	Advanced Configuration and Power Management Interface, Version 5.0
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EDD	- Enhanced Disk Drive Specification Version 1.1 - BIOS Enhanced Disk Drive Specification Version 3.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI	PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7
PCI Express	PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0
PMM	POST Memory Manager Specification, Version 1.01
SATA	Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
TPM	Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670) Common Criteria EAL4+ Certified FIPS 140-2 Certified TCG TPM Certified products list: http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
UHCI	Universal Host Controller Interface Design Guide, Revision 1.1
USB	Universal Serial Bus Revision 1.1 Specification Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 G1 Specification Universal Serial Bus Revision 3.1 G2 Specification
SMBIOS	System Management BIOS Reference Specification, Version 3.2

System Technical Specifications

Social and Environmental Responsibility

Eco-Label Certifications & Declarations This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program (CECP)
- The ECO declaration (TED)
- The ZCentral 4R is registered EPEAT® Gold in the US and Canada. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

Batteries

The battery in this product complies with EU Directive 2006/66/EC
Battery mass: 3g
Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Restricted Material Usage

This product meets the material restrictions specified in HP's General Specification for the Environment. HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis.

Low Halogen Statement

This product contains low-halogen printed circuit boards.

End-of-Life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:
[Sustainable Impact Report](#)
[Eco-label certifications ISO 14001 certificates](#)

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. [Product Disassembly Instructions](#)
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.

Packaging

HP Workstation product packaging meets the [HP's General Specification for the Environment](#)

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials

System Technical Specifications

- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting
- A multi-unit eco packaging option is available to institutional customers that uses less packaging material or has a lower volume footprint than conventional single-unit packaging. Please contact your sales representative for additional details.

Packaging Materials

Internal

Cushions and plastic bags made of low density polyethylene (LDPE).

External

Outer carton, accessories carton, and insert made of corrugated paper board.

System Technical Specifications

Manageability

Industry Standard Specifications

This product meets the following industry standard specifications for manageability functionality:

- DASH 1.1 (via Intel® LAN on motherboard)

Intel Active Management Technology (AMT)

Intel® Active Management Technology (AMT) 11.12

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.12 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- **NEW: Hardware Alerting (with special enablement for RPSU alerting)**
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help - a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance - pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts - automatically alert IT or service provider if issues arise
- Access Monitor - Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command – Creates memory dump for debug

Intel® vPro™ Technology

The HP ZCentral 4R Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor W-2200 product family featuring Intel® vPro™ Technology
- Intel® C422 chipset

Intel® I219LM GbE LAN

Remote Manageability Software Solutions

The HP ZCentral 4R Workstation is supported on the following optional remote manageability software consoles:

- [HP ZCentral Connect](#)
- Ivanti Management Suite
- Microsoft System Center Configuration Manager

For questions or support for manageability needs, please visit

<http://www.hp.com/go/easydeploy>

System Technical Specifications

System Software Manager

For easy deploy questions or support for SSM, please visit: <http://www.hp.com/go/ssm>

Service, Support, and Warranty

On-site Warranty and Service (**Note 1**): Three-years, limited warranty and service offering delivers on-site, next business-day (**Note 2**) service for parts and labor and includes free telephone support (**Note 3**) 8am - 5pm. Global coverage (**Note 2**) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/lookuptool>. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Product Change Notification

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors

Intel® Xeon® W-2223 3.6 2666 4C CPU
Intel® Xeon® W-2225 4.1 2933 4C CPU
Intel® Xeon® W-2245 3.9 2933 8C CPU

Hard Drives

1TB SATA 7200RPM Ent 3.5" HDD
1TB HP Z Turbo M.2 TLC 4R Kit SSD

Graphics

N/A

Technical Specifications - Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper-Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz) ¹	Intel® Turbo Boost Max Technology 3.0 (GHz) ¹	TDP (W)
Intel® Xeon® W Processors											
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	165
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120

¹Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

NOTE: Processors that do not have certain turbo functionality are denoted as N/A.

Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

SATA Hard Drives for HP Workstations	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Capacity	1TB
		Protocol	SATA
		Form Factor	3.5"
		Controller	AHCI
		Reliability (MTBF)	2.0M hours
		Rated Power On Hours	8760/yr
		Annualized Failure Rate (based on Rated POH)	<0.62%
		Rated for 24/7/365 operation	YES
		Physical Size (Height)	1 in; 2.54 cm
		Physical Size (Width)	4 in; 10.17 cm
		Media Diameter	3.5 in; 8.9 cm
		Interface	Serial ATA (6Gb/s), NCQ enabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s*
		Buffer	128MB
		Seek Time (typical reads, includes controller overhead, including settling)	Single Track 0.32ms* Average 7.45ms* Full Stroke 14.2ms*
		Operating Temperature	41° to 140° F (5° to 60° C)
	Performance	Sequential Read up to 226MB/s* Sequential Write up to 226MB/s*	
	Enterprise Class Features	High Reliability	

*Actual performance may vary.

Technical Specifications - Hard Drives

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity	2TB						
Protocol	SATA						
Form Factor	3.5"						
Controller	AHCI						
Reliability (MTBF)	2.0M hours						
Rated Power On Hours	8760/yr						
Annualized Failure Rate (based on Rated POH)	<0.62%						
Rated for 24/7/365 operation	YES						
Physical Size (Height)	1 in; 2.54 cm						
Physical Size (Width)	4 in; 10.17 cm						
Media Diameter	3.5 in; 8.9 cm						
Interface	Serial ATA (6Gb/s), NCQ enabled						
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*						
Buffer	128MB						
Seek Time (typical reads, includes controller overhead, including settling)	<table> <tr> <td>Single Track</td> <td>0.48ms*</td> </tr> <tr> <td>Average</td> <td>7.7ms*</td> </tr> <tr> <td>Full Stroke</td> <td>14.2ms*</td> </tr> </table>	Single Track	0.48ms*	Average	7.7ms*	Full Stroke	14.2ms*
Single Track	0.48ms*						
Average	7.7ms*						
Full Stroke	14.2ms*						
Operating Temperature	41° to 140° F (5° to 60° C)						
Performance	<table> <tr> <td>Sequential Read</td> <td>up to 226MB/s*</td> </tr> <tr> <td>Sequential Write</td> <td>up to 226MB/s*</td> </tr> </table>	Sequential Read	up to 226MB/s*	Sequential Write	up to 226MB/s*		
Sequential Read	up to 226MB/s*						
Sequential Write	up to 226MB/s*						
Enterprise Class Features	High Reliability						

*Actual performance may vary.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity	4TB						
Height	0.275 in; 0.7 cm						
Width	<table> <tr> <td>Media Diameter</td> <td>2.5 in; 6.36 cm</td> </tr> <tr> <td>Physical Size</td> <td>2.75 in; 6.99 cm</td> </tr> </table>	Media Diameter	2.5 in; 6.36 cm	Physical Size	2.75 in; 6.99 cm		
Media Diameter	2.5 in; 6.36 cm						
Physical Size	2.75 in; 6.99 cm						
Interface	Serial ATA (6Gb/s), NCQ enabled						
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*						
Buffer	128MB						
Seek Time (typical reads, includes controller overhead, including settling)	<table> <tr> <td>Single Track</td> <td>0.7ms*</td> </tr> <tr> <td>Average</td> <td>8.5ms*</td> </tr> <tr> <td>Full Stroke</td> <td>15.7ms*</td> </tr> </table>	Single Track	0.7ms*	Average	8.5ms*	Full Stroke	15.7ms*
Single Track	0.7ms*						
Average	8.5ms*						
Full Stroke	15.7ms*						
Rotational Speed	7,200 rpm						
Operating Temperature	32° to 140° F (0° to 60° C)						

*Actual performance may vary.

Technical Specifications - Hard Drives

SATA SSDs for HP Workstations

HP 256GB SATA 6Gb/s SSD

Capacity	256GB
Protocol	SATA
Form Factor	2.5"
Controller	AHCI
NAND Type	3D TLC
Endurance	192TBW (TB Written)
Reliability (MTTF)	1.5M hours
Physical Size (Height)	0.28 in; 0.7 cm
Physical Size (Width)	2.5 in; 6.36 cm
Interface	SATA 6Gb/s
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*
Operating Temperature	32° to 158° F (0° to 70° C)
Performance	
	Sequential Read 530MB/s (max)*
	Sequential Write 500MB/s (max)*
	Random Read 55K IOPS (max)*
	Random Write 83K IOPS (max)*

*Actual performance may vary.

HP 512GB SATA 6Gb/s SSD

Capacity	512GB
Protocol	SATA
Form Factor	2.5"
Controller	AHCI
NAND Type	3D TLC
Endurance	388TBW (TB Written)
Reliability (MTTF)	1.5M hours
Physical Size (Height)	0.28 in; 0.7 cm
Physical Size (Width)	2.5 in; 6.36 cm
Interface	SATA 6Gb/s
Synchronous Transfer Rate (Maximum)	Up to 550MB/s (Sequential Read)*
Operating Temperature	32° to 158° F (0° to 70° C)
Performance	
	Sequential Read 530 MB/s*
	Sequential Write 500 MB/s*
	Random Read 95K IOPS*
	Random Write 83K IOPS*

*Actual performance may vary.

Technical Specifications - Hard Drives

HP 1TB SATA 6Gb/s SSD	Capacity	1TB	
	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability (MTTF)	1.5M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	SATA 6Gb/s	
	Synchronous Transfer Rate (Maximum)	Up to 550MB/s (Sequential Read)*	
	Operating Temperature	32° to 158° F (0° to 70° C)	
	Performance	Sequential Read	530 MB/s*
		Sequential Write	500 MB/s*
Random Read		95K IOPS*	
Random Write		83K IOPS*	

*Actual performance may vary.

HP 1920GB SATA 6Gb/s SSD	Capacity	1920GB	
	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	4,400TBW (TB Written)	
	Reliability (MTTF)	2.0M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	SATA 6Gb/s	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s (Sequential Read)*	
	Operating Temperature	32° to 158° F (0° to 70° C)	
	Performance	Sequential Read	5340MB/s*
		Sequential Write	460 MB/s*
Random Read		93K IOPS*	
Random Write		74K IOPS*	
Enterprise Class Features	High Endurance NAND Power Loss Protection End-to-End Data Protection		

*Actual performance may vary.

Technical Specifications - Hard Drives

HP Enterprise Class 240GB SATA SSD

Capacity	240GB	
Protocol	SATA	
Form Factor	2.5"	
Controller	AHCI	
NAND Type	3D TLC	
Endurance	2,190TBW (TB Written)	
Reliability (MTTF)	2.0M hours	
Physical Size (Height)	0.28 in; 0.7 cm	
Physical Size (Width)	2.5 in; 6.36 cm	
Interface	6Gb/s SATA	
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	540 MB/s*
	Sequential Write	310 MB/s*
	Random Read	93K IOPS*
	Random Write	48K IOPS*
Enterprise Class Features	High Endurance NAND Power Loss Protection End-to-End Data Protection	

*Actual performance may vary.

HP Enterprise Class 480GB SATA SSD

Capacity	480GB	
Protocol	SATA	
Form Factor	2.5"	
Controller	AHCI	
NAND Type	3D TLC	
Endurance	4,380TBW (TB Written)	
Reliability (MTTF)	2.0M hours	
Physical Size (Height)	0.28 in; 0.7 cm	
Physical Size (Width)	2.5 in; 6.36 cm	
Interface	6Gb/s SATA	
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	540 MB/s*
	Sequential Write	460 MB/s*
	Random Read	93K IOPS*
	Random Write	74K IOPS*
Enterprise Class Features	High Endurance NAND Power Loss Protection End-to-End Data Protection	

*Actual performance may vary.

Capacity 960GB

Technical Specifications - Hard Drives

HP Enterprise Class 960GB SATA SSD	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	8,760TBW (TB Written)	
	Reliability (MTTF)	2.0M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	6Gb/s SATA	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
	Operating Temperature	32° to 158° F (0° to 70° C)	
	Performance	Sequential Read	540 MB/s*
		Sequential Write	460 MB/s*
		Random Read	93K IOPS*
Random Write		74K IOPS*	
Enterprise Class Features	High Endurance NAND Power Loss Protection End-to-End Data Protection		

*Actual performance may vary.

Technical Specifications - Hard Drives

**Performance PCIe
SSDs for HP
Workstations**

**HP Z Turbo Drive G2
256GB TLC SSD and
256GB SED TLC SSD**

Capacity	256GB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	200TB	
Reliability (MTBF)	1.5M hours	
Interface	M.2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, D5	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3400 MB/s*
	Sequential Write	2500 MB/s*
	Random Read	500K IOPS*
	Random Write	440K IOPS*

*Actual performance may vary.

**HP Z Turbo Drive G2
512GB TLC SSD and
512GB SED TLC SSD**

Capacity	512GB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
SED Support	Opal 2	
Endurance	300TBW (TB Written)	
Reliability (MTBF)	1.5M hours	
Interface	M.2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, D5	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3500 MB/s*
	Sequential Write	2900 MB/s*
	Random Read	460 K IOPS*
	Random Write	500K IOPS*

*Actual performance may vary.

Technical Specifications - Hard Drives

HP Z Turbo Drive G2 1TB TLC SSD

Capacity	1TB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	400TBW (TB Written)	
Reliability (MTBF)	1.5M hours	
Interface	M.2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, D5	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3500 MB/s*
	Sequential Write	3000 MB/s*
	Random Read	580K IOPS*
	Random Write	500K IOPS*

*Actual performance may vary.

HP Z Turbo Drive G2 2TB TLC SSD

Capacity	2TB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	500TBW (TB Written)	
Reliability (MTBF)	1.5M hours	
Interface	M.2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, D5	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3500 MB/s*
	Sequential Write	3000 MB/s *
	Random Read	600K IOPS*
	Random Write	500K IOPS*

*Actual performance may vary.

Technical Specifications - Hard Drives

HP Z Turbo Drive Dual Pro 512GB SSD

Capacity	512GB (one M.2 PCIe NVMe module)	
Protocol	PCIe	
Form Factor	M.2 in Half-height, half-length card	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	300TBW (TB Written)	
Reliability (MTBF)	1.5M hours	
Interface	PCI Express 3.0 x8 electrical x8 physical	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3500 MB/s*
	Sequential Write	2900 MB/s*
	Random Read	460 K IOPS*
	Random Write	500K IOPS*

*Actual performance may vary.

HP Z Turbo Drive Dual Pro 1TB SSD

Capacity	1TB (one M.2 PCIe NVMe module)	
Protocol	PCIe	
Form Factor	M.2 in Half-height, half-length card	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	400TBW (TB Written)	
Reliability (MTBF)	1.5M hours	
Interface	PCI Express 3.0 x8 electrical x8 physical	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3500 MB/s*
	Sequential Write	3000 MB/s*
	Random Read	580K IOPS*
	Random Write	500K IOPS*

*Actual performance may vary.

HP Z Turbo Drive Dual Pro 2TB SSD

Capacity	2TB (one M.2 PCIe NVMe module)	
Protocol	PCIe	
Form Factor	M.2 in Half-height, half-length card	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	500TBW (TB Written)	
Reliability (MTBF)	1.5M hours	
Interface	PCI Express 3.0 x8 electrical x8 physical	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read	3500 MB/s*
	Sequential Write	3000 MB/s *
	Random Read	600K IOPS*
	Random Write	500K IOPS*

*Actual performance may vary.

Technical Specifications - Graphics

GRAPHICS

**NVIDIA® Quadro® P400
2GB Graphics**

Form Factor	Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile Weight: 129 grams
Graphics Controller	NVIDIA® Quadro® P400 Graphics Card GPU: 256 CUDA cores Power: 30 Watts Cooling: Active
Bus Type	PCI Express 3.0 x16
Memory	Size: 2 GB GDDR5, 2000 MHz Memory Interface: 64-bit Memory Bandwidth: 32 GB/s
Connectors	3mDP 1.4 Outputs*
Maximum Resolution	DisplayPort™ 1.4: - up to 3x 4096 x 2160 x 24 bpp @ 60Hz - up to 1x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)
Image Quality Features	10-bit internal display processing pipeline 10-bit scan-out support
Display Output	3 mDP 1.4 Connectors
Shading Architecture	Full Microsoft DirectX 12 Shader Model 5.1
Supported Graphics APIs	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA C, CUDA C++, DirectCompute , OpenCL
Available Graphics Drivers	Microsoft Windows 10 Linux®
Notes	<p>HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html</p> <p>*P400, P600 and P1000 only have mini-DisplayPort™ (mDP) video ports.</p> <p>Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit:Two mDP-to-DP Adapters included</p> <p>Additional mDP-to-DP Adapters are available as Factory Configuration or Option Kit accessories:</p> <ul style="list-style-type: none"> - 2MY05AA - HP miniDP-to-DP Adapter Cables - 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Technical Specifications - Graphics

NVIDIA® Quadro® P1000 4GB Graphics	Form Factor	Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile Weight: 129 grams
	Graphics Controller	NVIDIA® Quadro® P1000 Graphics Card GPU: 640 CUDA cores Power: 47 Watts Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 4 GB GDDR5, 2500 MHz Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth
	Connectors	4 mDP 1.4 Outputs*
	Maximum Resolution	DisplayPort™ 1.4: - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)
	Image Quality Features	10-bit internal display processing pipeline 10-bit scan-out support
	Display Output	4 mDP 1.4 Connectors
	Shading Architecture	Full Microsoft DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA C, CUDA C++, DirectCompute, OpenCL
	Available Graphics Drivers	Microsoft Windows 10 Linux®
	Notes	<p>HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html</p> <p>*P400, P600 and P1000 only have mini-DisplayPort™ (mDP) video ports.</p> <p>Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit: Two mDP-to-DP Adapters included</p> <p>Additional mDP-to-DP Adapters are available as Factory Configuration or Option Kit accessories:</p> <ul style="list-style-type: none"> - 2MY05AA - HP miniDP-to-DP Adapter Cables - 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Technical Specifications - Graphics

NVIDIA® Quadro® P2200 5GB Graphics	Form Factor	Dimensions: 4.4”H x 7.9”L Single Slot Weight: 260 grams
	Graphics Controller	NVIDIA® Quadro® P2200 Graphics Card Power: 75 Watts Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 5GB GDDR5x Memory Bandwidth: 200 GB/s Memory Width: 160-bit
	Connectors	4x DisplayPort™ 1.4 Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included
	Maximum Resolution	Additional DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories. DisplayPort™ 1.4: - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - up to 4x 4096 x 2160 x 24 bpp @ 120Hz - supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)
	Image Quality Features	HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz 12-bit internal display pipeline (hardware support for 12-bit scanout on supported panels, applications and connection)
	Display Output	Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology, NVIDIA® Mosaic and nView. Maximum number of displays - 4 direct attached monitors Maximum number of monitors across all available outputs is 4
	Shading Architecture	Shader Model 5.1
	Supported Graphics APIs	OpenGL® 4.6 DirectX® 12.0 Vulkan 1.1 API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran software
	Available Graphics Drivers	Microsoft Windows 10 Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and ARB extensions HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

Technical Specifications - Graphics

Notes

1. Quadro P2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately.
2. Quadro P2000 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

NVIDIA® Quadro® RTX 4000 8GB Graphics

Form Factor

Full-Height Single Slot (4.4" Height x 9.5" Length)
Weight: 550 grams / 1.21 lbs

Graphics Controller

NVIDIA® Quadro® RTX 4000 Graphics
GPU: 2304 NVIDIA® CUDA® Parallel Processing Cores
Power: 160 Watts (125W graphics + 35W USB-C® PD)
Cooling: Active

Memory

8GB GDDR6
Memory Bandwidth: Up to 416 GB/s
Memory Width: 256-bit

Connectors

3x DisplayPort™ 1.4 and 1x VirtualLink
Quadro Sync connector (compatible with Quadro II Sync)
One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card.
After market option Kit: No video cable adaptor included with card.

DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution

DisplayPort™ 1.4:
- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution²
- up to 4x 5120 x 2880 x 24 bpp @ 60Hz
- up to 4x 3840 x 2160 x 24 bpp @ 120Hz
- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter):
- up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features

Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component.
HDCP 2.2 support over DisplayPort™, and HDMI connectors
NVIDIA® 3D Vision™ and other 3D stereo technologies
NVIDIA® Mosaic and nView

Display Outputs¹

Maximum number of displays
- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

Supported Graphics APIs

DirectX® 12, OpenGL® 4.6, OpenCL™ 1.0, Vulkan™ 1.0
Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

Technical Specifications - Graphics

Available Graphics Drivers

Windows® 10 64-bit
Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support Web site:

<http://welcome.hp.com/country/us/en/support.html>

Notes

- 1- Supports up to a total of 4 displays
- 2- Display must be capable of DSC or 2-cabled solution to obtain this resolution

NVIDIA® Quadro® RTX 5000 16GB Graphics

Form Factor

Full-Height Dual Slot (4.4" Height x 10.5" Length)
Weight: 975 grams + 75 grams extender

Graphics Controller

NVIDIA® QUADRO® RTX 5000
GPU: 3072 CUDA cores, 384 Tensor Cores, 48 RT Cores
Power: 265 Watts (230W graphics + 35W USB-C® PD)
Cooling: Active

Memory

16GB GDDR6
Memory Bandwidth: Up to 448 GB/s
ECC Memory (disabled by default)

Connectors

4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink
1x 8-pin and 1x 6-pin auxiliary power connectors
1x NVLink
Quadro Sync connector (compatible with Quadro II Sync)
3-pin mini-DIN connector via optional bracket
4-pin header for stereo signal

After market option Kit: no power adapter included with card.

DisplayPort™ to VGA, DisplayPort™ to DVI (single-link and dual-link), and DisplayPort™ to HDMI adapters available as accessories.

Maximum Resolution

DisplayPort™ 1.4:
- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution²
- up to 4x 5120 x 2880 x 24 bpp @ 60Hz
- up to 4x 4096 x 2160 x 24 bpp @ 120Hz
- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter):
- up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features

HDR support over DisplayPort™ 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b HEVC Encode)
HDCP 2.2 support over DisplayPort™ and HDMI connectors
NVIDIA 3D Vision™ technology
NVIDIA Mosaic and nView Desktop Management

Display Outputs

Maximum number of displays
- 4 direct attached monitors

Technical Specifications - Graphics

Maximum number of monitors across all available outputs is 4

GPU Architecture	NVIDIA® Turing
Supported Graphics APIs	DirectX®12, OpenGL® 4.6 Developer API support includes: CUDA C, CUDA C++, DirectCompute, OpenCL™, Java, Python, and Fortran
Available Graphics Drivers	Windows® 10 64-bit Linux® 64-bit HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included After market option kit: No adapters included

NVIDIA® Quadro® RTX 6000 24GB Graphics

Form Factor	Full-Height Dual Slot (4.4" Height x 10.5" Length) Weight: 995 grams + 75 grams extender
Graphics Controller	NVIDIA® QUADRO® RTX 6000 GPU: 4608 CUDA Cores, 576 Tensor Cores, 72 RT Cores Power: 295 Watts (260W graphics + 35W USB-C® PD) Cooling: Active
Memory	24GB GDDR6 Memory Bandwidth: Up to 672 GB/s ECC Memory (disabled by default)
Connectors	4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink 1x 8-pin and 1x 6-pin auxiliary power connectors 1x NVLink Quadro Sync connector (compatible with Quadro II Sync) 3-pin mini-DIN connector via optional bracket 4-pin header for stereo signal After market option Kit: no power adapter included with card.
Maximum Resolution	DisplayPort™ 1.4: - up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution ² - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - up to 4x 4096 x 2160 x 24 bpp @ 120Hz - supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST) HDMI 2.0 (requires DP to HDMI adapter):

Technical Specifications - Graphics

- up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features

HDR support over DisplayPort™ 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b HEVC Encode)
HDCP 2.2 support over DisplayPort™ and HDMI connectors
NVIDIA 3D Vision™ technology
NVIDIA Mosaic and nView Desktop Management

Display Outputs

Maximum number of displays
- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

GPU Architecture

NVIDIA® Turing

Supported Graphics APIs

DirectX®12, OpenGL® 4.6
Developer API support includes: CUDA C, CUDA C++, DirectCompute, OpenCL™, Java, Python, and Fortran

Available Graphics Drivers

Windows® 10 64-bit
Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support Web site:

<http://welcome.hp.com/country/us/en/support.html>

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included
After market option kit: No adapters included

Technical Specifications - Graphics

NVIDIA® Quadro® RTX 8000 48GB Graphics	Form Factor	Full-Height Dual Slot (4.4" Height x 10.5" Length) Weight: 1070 grams / 2.35 lbs
	Graphics Controller	NVIDIA® Quadro® RTX 8000 Graphics GPU: 4608 CUDA Cores, 576 Tensor Cores, 72 RT Cores Power: 295 Watts Cooling: Active
	Memory	48GB GDDR6 memory Memory Bandwidth: Up to 672 GB/s Memory Width: 384-bit
	Connectors	4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink 1x 8-pin and 1x 6-pin auxiliary power connectors 1x NVLink Quadro Sync connector (compatible with Quadro II Sync) 3-pin mini-DIN connector via optional bracket 4-pin header for stereo signal After market option Kit: no power adapter included with card. DisplayPort™ to VGA, DisplayPort™ to DVI and DisplayPort™ to HDMI adapters available as accessories.
	Maximum Resolution	DisplayPort™ 1.4: - up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution ² - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - up to 4x 4096 x 2160 x 24 bpp @ 120Hz - supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST) HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz
	Image Quality Features	Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component. HDCP 2.2 support over DisplayPort™ and HDMI connectors NVIDIA® 3D Vision™ and other 3D stereo technologies NVIDIA® Mosaic and nView
	Display Outputs¹	Maximum number of displays - 4 direct attached monitors Maximum number of monitors across all available outputs is 4
	Supported Graphics APIs	DirectX® 12, OpenGL® 4.6, OpenCL™ 1.0, Vulkan™ 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute, OpenCL™, Java, Python, and Fortran
	Available Graphics Drivers	Windows® 10 64-bit Linux® 64-bit HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Notes	1- Supports up to a total of 4 displays

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

Integrated Intel I219 PCIe GbE Controller	Connector	RJ-45
	Controller	Intel I219 GbE platform LAN connect networking controller
	Data Rates Supported	10/100/1000 Mbps
	Boot ROM Support	PXE, UEFI, iSCSI Boot
	Connect Speed LED Indicators	Link/Activity LED <ul style="list-style-type: none"> • Off = No link • Blinking = Activity
		Speed LED <ul style="list-style-type: none"> • Off = 10Mbps • Amber = 100Mbps • Green = 1000Mbps

Management Capabilities Wake-On-LAN, Intel® Active Management Technology™ (AMT) 11.12

Integrated Marvell AQC-107	Connector	RJ-45
	Controller	Marvell AQtion AQC-107
	Data Rates Supported	10/100/1000 Mbps, 2.5/5/10 Gbps
	Boot ROM Support	PXE, UEFI
	Connect Speed LED Indicators	Link/Activity LED <ul style="list-style-type: none"> • Off = No link • Blinking = Activity
		Speed LED <ul style="list-style-type: none"> • Amber = < 10 Gbps • Green = 10Gbps

Management Capabilities Wake-On-LAN

Intel® I210-T1	Networking Interface	RJ-45
	System Interface	PCI Express 2.1 x1
	Networking Speeds Supported	10Mbps, 100Mbps, 1Gbps
	Cabling (up to 100m)	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps
	Power Consumption (active-typical)	0.81W
	Physical Dimensions	Length: 6.7cm (2.64 inches) (Bracket) Width: 1.8cm (0.709 inches) Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

Technical Specifications - Networking and Communications

Connect Speed LED Indicators	<p>Link/Activity LED</p> <ul style="list-style-type: none"> • Off = No link • Blinking = Activity <p>Speed LED</p> <ul style="list-style-type: none"> • Off = 10Mbps • Green = 100Mbps • Amber = 1Gbps
Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
Hardware Certifications	USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI, Australia/New Zealand: CTICK, Korea: KCC, Canada: ICES-003/NMB-003

Intel® X550-T2	Networking Interface	2 x RJ-45
	System Interface	PCI Express 3 x4
	Networking Speeds Supported	100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps
	Cabling (up to 100m)	Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6a (or higher) for 10Gbps
	Power Consumption (active-typical)	3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps
	Physical Dimensions	5.2 in x 2.7 in (without bracket)
	Connect Speed LED Indicators	<p>Link/Activity LED</p> <ul style="list-style-type: none"> • Off = No link • Blinking = Activity <p>Speed LED</p> <ul style="list-style-type: none"> • Off = No link • Amber = <10Gbps • Green = 10Gbps
	Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
	Hardware Certifications	USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI, Australia/New Zealand: CTICK, Korea: KCC, Canada: ICES-003/NMB-003

Technical Specifications - Networking and Communications

**Allied Telesis
AT-2914SX/LC-901 1GB LC
Fiber NIC**

Networking Interface

System Interface

Networking Speeds Supported

Cabling

Power Consumption (active-typical)

Physical Dimensions

Connect Speed LED Indicators

Operating Temperature

Hardware Certifications

1Gb LC Fiber 850 nm

PCIeG2 x1, Half Height, Half Length

1000Base-X (1 Gbps)

50/125 μm (core/cladding) multimode fiber optic cable
up to 500m

62.5/125 μm (core/cladding) multimode fiber optic cable
up to 220m

1.5 Watts

8.8 cm x 6.9 cm (3.5 in x 2.7 in)

ON: 1Gbps Link OFF: Link down

-25°C to 70°C (-13°F to 158°F)

IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs),
IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow
control auto-negotiation), IEEE 802.3z (1000 Base-X),
IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-
TICK, VCCI

Date of change:	Version History:		Description of change:
December 17, 2020	From v1 to v2	Changed	Storage / Hard Drives and Graphics sections
February 1, 2021	From v2 to v3	Changed	Processors and NETWORKING AND COMMUNICATIONS sections
March 1, 2021	From v3 to v4	Changed	Overview and Other Hardware sections
April 13, 2021	From v4 to v5	Changed	Racking and Physical Security sections
April 21, 2021	From v5 to v6	Changed	Format page 2 and 3

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